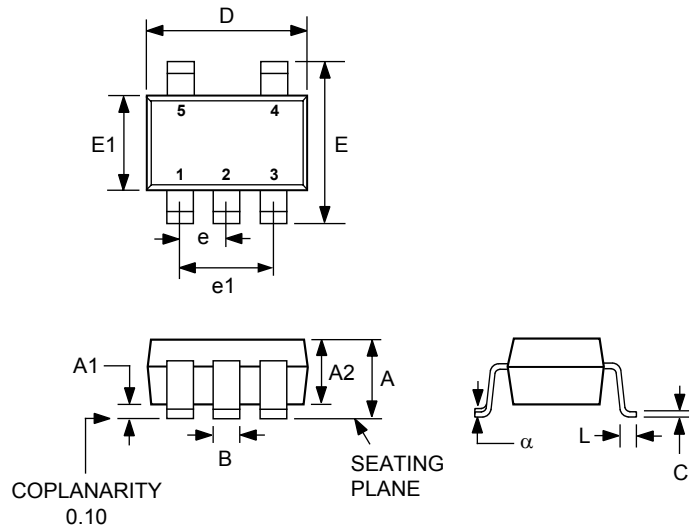


5-Lead SOT Package



Symbol	Millimeters	
	MIN	MAX
A	-	1.45
A1	0.0	0.15
A2	0.90	1.30
B	0.30	0.50
C	0.08	0.22
D	2.90 BSC	
E	2.80 BSC	
E1	1.60 BSC	
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60
α	0°	8°

Compliant to JEDEC Standard MO178

Controlling dimensions are in millimeters

This package is RoHS compliant, and conform to Halide free limits.

Soldering Temperature Resistance:

[a] Package is IPC/JEDEC Std 020D Moisture Sensitivity Level 1

[b] Package exceeds JEDEC Std No. 22-A111 for Solder Immersion resistance; packages can withstand 10 s immersion @ < 270 °C

Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.25 mm per end. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 mm per side. D and E1 dimensions are determined at datum H.

The package top may be smaller than the package bottom. Dimension D and E1 are determined at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body. D and E1 dimensions are determined at datum H.